

# Sungtech

COMTEK ELECTRONICS CO., LTD.

## PRODUCT SPECIFICATION

## **PRODUCT NAME**

**MINI USB** 

## **SPECIFICATION NUMBER**

DOC. NO.:

**AUTHOR**:

**DATE:** 

**REV.:** A

<u>APPROVED</u>	<u>CHECKED</u>
SIGNED:	SIGNED:
DATE:	DATE:

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# Sungtech specification

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#### 1.0 SCOPE

This document contains general suntech requirements, qualification requirements, and those specific electrical and mechanical requirements.

#### 2.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

See drawings and any other sections of this specification for the relevant reference documents. In cases where the product specification differs from the product drawings, the product drawings take precedence.

## 3.0 RATINGS

3.1.Rated Current	AC 0.5A
J.I. Nated Culterit	AC 0.3A

3.2.Rated Voltage AC 5V

3.3. Operating Temperature Range  $-0^{\circ}$ C to  $+50^{\circ}$ C

3.4. Storage Temperature Range  $-20^{\circ}$ C to  $+85^{\circ}$ C

 $+20^{\circ}C$ 3.5. Nominal Temperature Rating

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#### 4.0 MATERIAL SPECIFICATIONS

4.1. Plastic body: LCP.

4.2. Shell: Phosphor Bronze

Tin Plating

4.3. Contact: Phosphor Bronze

Solder area: Tin Contact area: Au 5u"

#### 5.0 EXAMINATION OF PRODUCT

**Test Condition** Requirement <u>Item</u>

5.1. Examination of product (Outward Appearance Structure) EIA364-18

1. Outward Appearance shall be good without such injurious problem

Shall be confirmed with eyes by using magnifying glass 5x.

### 6.0 ELECTRICAL PERFORMANCE SPECIFICATIONS

<u>Item</u>	<u>Test Condition</u>	<u>Requirement</u>	
6.1. Low Level Contact Resistance	EIA 364-23	$50$ m $\Omega$ (Max)	
test point	Mated connector with dry circuit of 20mV, 100mA max.		
6.2.Insulation Resistance	EIA 364-21	$100M\Omega(Min.)$	
	Unmated connector with 500VDC between adjacent contacts.		
6.3. Dielectric Withstanding Voltage	EIA 364-20	0.5mA(Max.) leakage of	
	Unmated connector with 100VAC for 1 minute between adjacent contacts.	current	
6.4 Contact Capacitance	EIA 364-30	2pF(Max.)	
	Unmated connector with 2pF between adjacent contacts		

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### 7.0 MECHANICAL PERFORMANCE SPECIFICATIONS

Item
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## Requirement

7.1.Durability



EIA 364-09

Mate contacts at rate of 200 cycles per hour max. to 5,000 cycles.

**Test Condition** 

Shall meet visual requirement, show no physical damage.

7.2. Random Vibration

EIA 364-28 Test condition V Test Letter A .Subject mated connectors to 5.35G's rms. 15 minutes in each of 3 mutually perpendicular planes.

No discontinuities of 1  $\mu$  sec or longer duration.

Shall meet visual requirement, show no physical damage.

7.3.Insertion Force



EIA 364-13

Measure force necessary to mate assemblies at rate of 12.5mm/min (max.)

35N (Max.)

7.4.Extraction Force



EIA 364-13

Measure force necessary to mate assemblies at rate of 12.5mm/min (max.)

1N (Min.)

7.5.Physical Shock

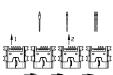
EIA 364-27 Test condition A

Subject mated connectors to 50G's half-sine shock pulses of 11ms duration.3 shocks in each direction applied along 3 mutually perpendicular planes, 18 total shock

1. No discontinuities of 1  $\mu$  sec or longer duration.

2. Shall meet visual requirement, show no physical damage.

7.6.Retention force



Measured by pulling the pin and adjacent pin which have been inserted into the plastic body at the speed of 0.2 mm/s.

3 N (Min.) for each pin.

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## 8.0 ENVIRONMENTAL PERFORMANCE SPECIFICATIONS

<u>Item</u>	Test Condition		<u>1</u>	Requirement	
8.1.Thermal shock	8.1.Thermal shock EIA 364-32 Test condition I				
<u>t3</u>	Stage	Temp	Time	Shall meet visual requirement,	
t2/\_t4	t1	-55°C	15~30	show no physical damage.	
	t2	-55~+8	min		
t1	t3	$5^{\circ}C$	5 min		
	t4	+ 85°C	15~30 min		
		+85~-5 5°C	5 min		
	Test time	Test time: 10 cycle			
8.2.Humidity Life	EIA 364-31 Test condition A Method ∭(See the following figure. Follow step1 to step7a.)		ollowing	Shall meet visual requirement, show no physical damage.	
	Subject mated connectors to 168 hours (7 complete cycle)				
8.3.Solderability	EIA 364-52			The surface of the portion to be	
	After one	er one hour steam aging.		soldered shall at least 95% covered with new solder coating, as specified in Category 2	
				( 1.0 hour±5minutes ).	
8.4.Solder Heat Resistance	See the following figure.		re.	No degradation in performance of physical damages after test.	

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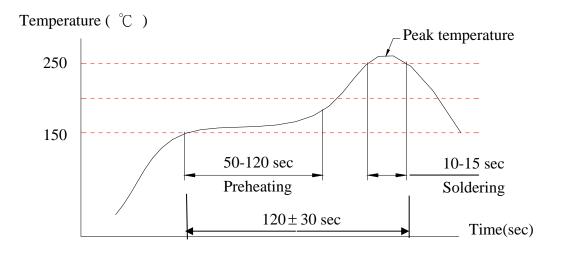
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#### 8.0 ENVIRONMENTAL PERFORMANCE SPECIFICATIONS

Peak temperature: 260°C

Soldering temperature: 250°C

Preheating temperature: 150-175°C



### SOLDERING TEMPERATURE/TIME PROFILE

9.0 PACKING Tape & Reel